

AC-M25

Description

AC-M25 is a liquid blend with an aromatic trimellitic anhydride backbone for curing epoxy resins. AC-M25 combines high Tg, improved thermal aging, and vibrations dampening. In addition, epoxy resins cured with AC-M25 have high heat deflection temperatures, even in hot and wet environments, and have excellent chemical and electrical properties.

Chemical Name: Trimellitic Dianhydride Derivative CAS Number: 1732-97-97-4 and 25134-21-8

Typical Applications

Potting for high temperature outdoor applications

Encapsulation of electrical and electronic components

Military composites with high HDT in hot/wet conditions

Specifications

Appearance	Amber viscous liquid	
% Anhydride	38.0 - 38.4	
% Free Acid	< 2.0	
Color (Gardner)	4 - 7	
Specific Gravity	1.25 - 1.27	
Refractive Index	1.50205 - 1.5225	
Viscosity at 25°C	2200 - 2700	

Typical Formulation

Parts by Weight

	,
Epoxy Resin (epoxy equivalent 185)	100 phr
AC-M25	90 phr
MI (Methyl Imidazole)	1

Cure schedule: 1 hr at 120°C followed by 2 hrs at 175 °C

Properties

Тд	165
Weight Gain 24hrs Immersion in Water at 180°F	<0.5%
Tensile Strength, psi	12,200
Tensile Strength After 1000 hrs at 150°C, psi	12,100
Elongation %	3.1
Elongation % after 1000 hrs @ 150°C	3.0

Packaging

Drums: 55 gallon metal drum (485 lbs. net)

Pail: 5 gallon plastic (45 lbs. net)



Shelf-Life

Product should be stored in a dry and cool area. Containers should remain tightly sealed to avoid moisture absorption, and product hydrolysis. Under these conditions, the product shelf-life is 12 months.

Notice: No freedom from any patent owned by Broadview or others is to be inferred. Broadview assumes no obligation or liability for the information in this document. The information contained herein is believed to be correct, and corresponds to the latest state of scientific knowledge. However, no warranty is made, either expressed or implied, regarding its accuracy or the results to be obtained from such information. No statement is intended or should be construed as a recommendation to infringe any existing patent.